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FOR

METHOD AND APPARATUS FOR SEN-REF EQUALIZATION

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METHOD AND APPARATUS FOR SEN-REF EQUALIZATION

BACKGROUND OF THE INVENTIONField of the Invention

5 The invention generally relates to memory technology and more specifically relates to sense amplifiers in FLASH memory devices.

Description of the Related Art

Most memory technology employs sense amplifiers. These sense amplifiers are

10 typically designed for low current inputs with high gain and rapid response times. However, memory technology also often involves selecting a particular cell and letting that cell pull a node down or up, to a different value from what the node is biased to when no cell is selected. That node is typically the input node of the sense amplifier. As a result, the fastest sense amplifier is of little use if the input node can only be pulled
15 to a different voltage slowly by the memory cell.

One method for providing a memory cell that can rapidly pull a node up or down is to use a large transistor in the memory cell, thus allowing for high current which may pull the node to the desired voltage. However, the larger the transistor, the more space the memory cell requires, and therefore the lower the density of memory cells can be on
20 a given memory chip. Furthermore, a larger transistor may have increased capacitive coupling effects which will lead to a slower transition from a non-conductive to a conductive state, resulting in a property of the larger transistor defeating the purpose of having the larger transistor.

Beyond problems with how quickly a node may be pulled down or up, problems may arise when comparing a reference cell and memory cell response due to settling time on the inputs to the sense amplifier. If the reference cell has a greater effect on the reference input node initially than the memory cell has on the sense input node,

5 then the sense amplifier may generate a signal which is false early in the cycle, before the sense input node transitions properly. This means that the delay associated with the sense amplifier may be longer than would otherwise be expected or preferable.

BRIEF DESCRIPTION OF THE DRAWINGS

The present invention is illustrated by way of example and not limitation in the accompanying figures.

Figure 1 illustrates an embodiment of sensing circuitry suitable for use with a
5 FLASH cell.

Figure 2 illustrates an alternate embodiment of sensing circuitry suitable for use
with a FLASH cell.

Figure 3 illustrates another alternative embodiment of sensing circuitry suitable
for use with a FLASH cell.

10 Figure 4A illustrates a simulation of a FLASH cell such as the cell of Figure 1.

Figure 4B illustrates a simulation of a FLASH cell such as the cell of Figure 1.

Figure 4C illustrates a simulation of a FLASH cell such as the cell of Figure 1.

Figure 4D illustrates a simulation of a FLASH cell such as the cell of Figure 1.

Figure 5 illustrates an embodiment of a FLASH integrated circuit.

15 Figure 6 illustrates an embodiment of a method of sensing a FLASH cell.

DETAILED DESCRIPTION

A method and apparatus for sen-ref equalization is described. In the following description, for purposes of explanation, numerous specific details are set forth in order to provide a thorough understanding of the invention. It will be apparent, however, to one skilled in the art that the invention can be practiced without these specific details. In other instances, structures and devices are shown in block diagram form in order to avoid obscuring the invention.

Reference in the specification to "one embodiment" or "an embodiment" means that a particular feature, structure, or characteristic described in connection with the embodiment is included in at least one embodiment of the invention. The appearances of the phrase "in one embodiment" in various places in the specification are not necessarily all referring to the same embodiment. Likewise, alternative or separate embodiments are not necessarily mutually exclusive of other embodiments.

The low voltage sensing in FLASH memories is carried out through use of a common mode current mirror (current source) and kicker circuitry in the sensing circuitry. The common mode current mirror provides current generally sufficient to satisfy the current drain from the bias network, and the kicker circuitry provides additional pullup current (charge) relative to the current supplied by the column load in the sensing circuitry. By providing both of these additional elements, the column load may be sized and designed as a more resistive load suitable for providing a significant voltage swing between a high and a low voltage on a FLASH cell.

The voltage swing between the high and the low voltage on the FLASH cell is sensed by the actual sense amplifier, and amplifiers generally perform better with

increased voltage differentials on the inputs of the amplifier. In a FLASH design, the sense amplifier may sense the difference between a reference FLASH cell and a FLASH cell to be sensed. The voltage swing has an effect on the difference between the voltages produced by the relatively stable reference FLASH cell and the FLASH cell
5 to be sensed. The voltage produced by the FLASH cell to be sensed may differ more from the voltage produced by the reference FLASH cell.

As will be appreciated, transient or bias differences between the sense and reference inputs of the sense amplifier can prolong the time needed to achieve a stable output from the sense amplifier. Additionally, settling time on the inputs of the sense
10 amplifier can similarly prolong the time needed to achieve a stable output on the sense amplifier. As such, equalizing the inputs prior to allowing the FLASH cell to be sensed and the reference FLASH cell can be useful to reduce the time needed to achieve the desired stable output on the sense amplifier.

Note that the invention is described with reference to embodiments incorporating
15 FLASH cells which are known to those skilled in the art. However, it will be appreciated that other forms of persistent memory storage locations (such as EPROM cells for example) may be utilized in conjunction with the invention without exceeding the spirit and scope of the invention. A persistent memory storage location, such as a FLASH cell, typically may be programmed to store a 'one' or a 'zero' which represents a binary
20 digit or bit. The actual 'one' or 'zero' as stored in the persistent memory storage location may be stored as a charge level or some other measurable property of the persistent memory storage location.

Illustrated in Figure 1 is an embodiment of sensing circuitry for a FLASH cell array. Sense input 110 is coupled to a FLASH cell to be sensed (not shown). Ref input 120 is coupled to a FLASH reference cell (also not shown). Equalize signal 130 is coupled to a first or gate node of a transistor 135. Transistor 135 has a second node 5 coupled to sense input 110 and a third node coupled to ref input 120. Thus, equalize signal 130 may be used to control whether sense input 110 is coupled to ref input 120, thereby allowing for equalization between sense input 110 and ref input 120.

First and second drain bias networks 150 are each coupled to sense input 110 and ref input 120 respectively, and each network 150 is controlled by a common drain 10 bias enable input 140. The first drain bias network 150 produces a SIN signal 160 which represents an input to the sense amplifier 180 corresponding to the sense input 110. The second drain bias network 150 produces a RIN signal 170 which represents 15 an input to the sense amplifier 180 corresponding to the ref input 120. The drain bias networks 150 operate to make the output of a FLASH cell to be sensed (or a reference 20 FLASH cell) into an output suitable for use as an input to a differential amplifier such as sense amplifier 180. In one embodiment, a FLASH cell output can be measured as a current, and the drain bias network operates to convert this current to a voltage for sensing purposes. Note, however, that this conversion does not change anything other than the manner of sensing of the value of the FLASH cell. Sense amplifier 180 compares the two inputs to produce a sense amplifier output 190.

By equalizing the sense input 110 and the ref input 120, the corresponding inputs to the sense amplifier 180 may be expected to rise and fall relatively closely. In particular, if the sense input 110 and the ref input 120 are equalized until the FLASH

cell to be sensed and the reference FLASH cell are coupled thereto, one can expect that this equalization will tend to minimize changes in polarity of the voltage difference between the sense input 110 and the ref input 120 during the time for sensing those inputs. This implies that the sense amplifier 180 will not change its output 190 once it

5 determines the polarity of the differential between the two inputs. This in turn leads to a faster stable output signal 190 from the sense amplifier 180.

Turning to Figure 2, an alternative embodiment of sensing circuitry and a FLASH cell is illustrated. FLASH cell 204 is made up of a floating gate NMOS transistor 201 coupled to ground at its first node and to a first node of column select NMOS transistor 207 at transistor 201's second node. Note that in most MOSFET transistors, a first or second node may be either a source or drain of the transistor, while in bipolar junction transistors the first or second node may be either a collector or emitter. Column select signal 210 is coupled to the gate of transistor 207. The second node of transistor 207 is coupled to the gate of transistor 213 and to the first node of transistor 216. The first node of transistor 213 is coupled to ground, and the second node of transistor 213 is coupled to the gate of transistor 216, the gate of transistor 222, and the first node of transistor 219. The second node of transistor 216 is coupled to the first node of transistor 222 and to the first node of transistor 225, and the node at which this coupling is made is referred to as SINA 231. The gate and the second node of transistor 219

10 are both coupled to a power supply such as Vcc. Likewise, the gate and the second node of transistor 222 and the gate and the second node of transistor 225 are coupled to a power supply.

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Also coupled to the node SINA 231 is the second node of transistor 228 and the first input of sense amplifier 234. Coupled to the first node of transistor 238 and the first node of transistor 243 is a power supply. Coupled to the gate of transistor 228 and the gate of transistor 243 is current adjust input 240. Coupled to the first node of 5 transistor 243 is node SINB 246. Node 246 is also coupled to the second input of sense amplifier 234, the first node of transistor 249, the first node of transistor 252, and the second node of transistor 258. The output of sense amplifier 234 is coupled to data 237.

The second node and gate of transistor 252 are coupled to a power supply, as is 10 the second node of transistor 249. The gate of transistor 249 is coupled to the gate of transistor 258, the first node of transistor 255 and the second node of transistor 261. The first node of transistor 258 is coupled to the gate of transistor 251 and to the 15 second node of transistor 264. The gate and the second node of transistor 255 are coupled to a power supply. The first node of transistor 261 is coupled to ground. The first node of transistor 264 is coupled to the second node of floating gate transistor 267. The first node of floating gate transistor 267 is coupled to ground. Reference cell 270 is 20 formed by floating gate transistor 267, which is preferably programmed to serve as a reference voltage similar to that of a FLASH cell in either a programmed or erased configuration. Alternatively, reference cell 270 may be programmed to serve as a reference voltage nearly midway between a 'programmed' and an 'erased' voltage of a FLASH cell, thereby supplying a trip voltage to sense amplifier 234.

As illustrated in this embodiment, transistor 228 may be adjusted to provide current sufficient to satisfy most of the demand from transistor 216. As a result,

transistor 225 may be implemented as the column load for cell 204. Similarly, transistor 243 may provide current sufficient to satisfy most of the demand from transistor 258, thus allowing transistor 252 to act as a column load for reference cell 270.

Equalization transistor 275 has a first node coupled to the first node of transistor

- 5 207, a second node coupled to the first node of transistor 264, and a third node coupled to equalize signal 280. In one embodiment, equalize signal 280 causes equalization transistor 275 to conduct until transistors 207 and 264 couple the cells (204, 270), thereby equalizing the inputs to the sense amplifier 234 prior to changes induced by the cells (204, 270) to be sensed. Also note that the exact connection of transistor 275 to other elements in the circuit is not necessarily crucial, so long as it can operate to equalize the inputs to the sense amplifier and thereby settle both the inputs and the corresponding output. Here, transistor 275 is connected to circuit elements near the inputs of the drain bias circuitry, but that need not be the only useful location within the circuit. Furthermore, layout positioning of transistor 275 may or may not be critical,
- 10 15 depending on many other factors affecting circuit design as understood by those skilled in the art.

In one embodiment, transistors 228 and 243 provide common mode current

- 20 necessary to run or power the drain bias circuitry. Transistors 225 and 252 provide the column load associated with the drain bias circuitry, and may be sized to achieve a highly resistive (and therefore sensitive) load to the cells 204 and 270. Transistors 213, 216, 219 and 222 provide a kicker which speeds up the stabilization of SINA 231 in response to a change at the first node of transistor 216, such as coupling of the cell 204. Similarly, transistors 249, 255, 258, and 261 provide a kicker which speeds up the

stabilization of SINR 246 in response to a change at the first node of transistor 261, such as coupling of the cell 270. Transistors 213, 216, 219, 222, 225 and 228 thus make up a first drain bias circuit, and transistors 243, 249, 252, 255, 258 and 261 make up a second drain bias circuit.

- 5 Illustrated in Figure 3 is another alternative embodiment of sensing/biasing circuitry for use with a FLASH cell. SHREF signal 310 is suitable for coupling to a reference FLASH cell. SHSEN signal 320 is suitable for coupling to a FLASH cell to be sensed. Equal transistor 335 is coupled at a first node to the node of SHREF 310, at a second node to the node of SHSEN 320 and at a third node to the equalize signal 330.
- 10 Two drain bias networks 350 are provided, one coupled to SHREF 310 and another coupled to SHSEN 320.

Each drain bias network 350 has a control input set 340 associated therewith, allowing for tuning of the drain bias networks. In one embodiment, the control input set 340 of the first drain bias network 350 is coupled to the same signals that are coupled 15 to the control input set 340 of the second drain bias network 350, thereby assuring nearly identical operation of the circuits. Furthermore, the control input sets 340 may be used as enable inputs. One drain bias network 350 produces an output RIN 360 which is produced from the SHREF signal 310 and which is suitable for coupling to the reference input of a sense amplifier. The other drain bias network 350 produces an 20 output SIN 370 which is produced from the SHSEN signal 320 and which is suitable for coupling to the sense input of a sense amplifier.

Turning to Figure 4A, an illustration of a simulation of sensing a FLASH cell programmed to a 'one' without an equalization pulse is provided. Note that the

equalization pulse 410 is illustrated, for ease of comparison with simulations utilizing the equalization pulse. The drain bias enable signal 450 is illustrated as high (enabled in one embodiment). Furthermore, the sense amplifier out signal 440 is illustrated as high, since the inputs do not perturb the sense amplifier enough to cause the output to swing low. The RIN 430 and SIN 420 signals may be seen to rise and to cross each other several times. These signals are the inputs to the sense amplifier, and the time it takes for them to stabilize leads to the time necessary to achieve a stable output from the sense amplifier.

Turning to Figure 4B, an illustration of a simulation of sensing a FLASH cell programmed to a ‘one’ with an equalization pulse is provided. Note that in this simulation, the two signals RIN 430 and SIN 420 move in near lockstep due to the coupling of the equalization circuit, thus eliminating the crossover behavior seen in Figure 4A. While the instability of the sense amplifier output 440 may be seen here, it is apparent that after the second dip on the output, the output may be expected to be stable.

Turning to Figure 4C, an illustration of a simulation of sensing a FLASH cell programmed to a ‘zero’ with an equalization pulse is provided. Again, in this simulation, the two inputs RIN 430 and SIN 420 move in tandem during the equalization period, with only slight differences, and then separate in a monotonic manner with respect to the differential. No crossover behavior is illustrated. Turning to Figure 4D, an illustration of a simulation of sensing a FLASH cell programmed to a ‘zero’ without an equalization pulse is provided. In this simulation, the crossover behavior of the SIN 420

and RIN 430 signals is repeated several times, causing a long delay before the sense amplifier output 440 is at a stable, useful value.

Figure 5 illustrates an embodiment of a FLASH integrated circuit. Addressing circuitry 510 receives address signals (not shown) and translates those signals into 5 column select 550 and row select 560 (each of which may be implemented as a bus of individual signals in one embodiment). FLASH cell array 520 receives column select 550 and row select 560, and the combination of the two results in selection of a single FLASH cell from the array 520 in one embodiment. FLASH cell array 520 may also receive a data input 570 which is suitable for programming a selected cell. FLASH cell 10 array supplies a signal (voltage/current) to comparison circuitry 530, and the supplied signal is derived from or comes directly from the selected cell. Comparison circuitry receives the signal supplied by FLASH cell array 520, and compares that signal to a reference signal. The comparison results in a data output signal 580 which is generated by comparison circuitry 530. Power and bias circuitry 540 is coupled to each 15 of the other portions of the FLASH integrated circuit, and may supply power and bias voltages and currents. Circuitry 540 may also supply such signals as programming and erase signals as appropriate, and may embody a charge pump for producing voltages greater than a supply voltage of the FLASH integrated circuit.

Turning to Figure 6, an embodiment of the method of operation of low voltage 20 sensing in flash memories is illustrated. It will be appreciated that the blocks in Figure 6 are depicted in serial fashion but may actually be implemented in a parallel or simultaneous fashion. In block 610, the FLASH cell is selected, such as by selecting an appropriate column select signal and thereby connecting a FLASH cell to the sensing

apparatus. At block 620, an equalization pulse is begun, causing the inputs used for the FLASH cell to be sensed and the reference FLASH cell to be coupled together and to move substantially together along a V-I curve (a plot of voltage versus current). At block 630, the FLASH cell is loaded by the sensing apparatus, such that the FLASH cell
5 will conduct current from the load to ground if it is programmed in a state to conduct. At block 640, current is supplied from the load to the FLASH cell. At block 650, the equalization pulse is ended, allowing the sense inputs for the reference FLASH cell and FLASH cell to be sensed to decouple. At block 660, the difference in voltage between the connected FLASH cell and a reference FLASH cell is measured, as by a sense
10 amplifier. It will be appreciated that the measurement is a comparison between a voltage level produced by a reference FLASH cell and a voltage level produced by the selected FLASH cell in one embodiment which may involve measurement of both voltage levels. Furthermore, it will be appreciated that loading the FLASH cell (or the reference FLASH cell) may also include supplying current to the FLASH cell (or
15 reference FLASH cell).

By using a column load in conjunction with a current mirror, the measured difference in voltage may be detected relatively easily, as the voltage swing that occurs when the column load reacts to a change in current may be fairly high. Furthermore, by using the equalization pulse, the two inputs may be kept equal during what would normally be a transient condition subject to short-term variations in performance.
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In the foregoing detailed description, the method and apparatus of the present invention has been described with reference to specific exemplary embodiments thereof. It will, however, be evident that various modifications and changes may be

made thereto without departing from the broader spirit and scope of the present invention. In particular, the advantages conferred by the kicker and the common mode current source may be viewed as separate and cumulative, such that neither is necessarily required in a circuit to derive the advantages conferred by the other.

- 5 Furthermore, it will be appreciated that a device may be coupled to another device in a direct or an indirect manner, such that the transistor 222 may be said to be coupled both to transistor 225 and to FLASH cell 204. Moreover, with respect to flow diagrams and processes, it will be appreciated that a flow diagram organized in a linear or step-wise fashion may represent operations which may be reorganized to occur in a different order, or to occur in a parallel fashion for example. The present specification and figures are accordingly to be regarded as illustrative rather than restrictive.
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